

SUBMINIATURE SOLID STATE LAMP

KM2520SGD03 SUPER BRIGHT GREEN

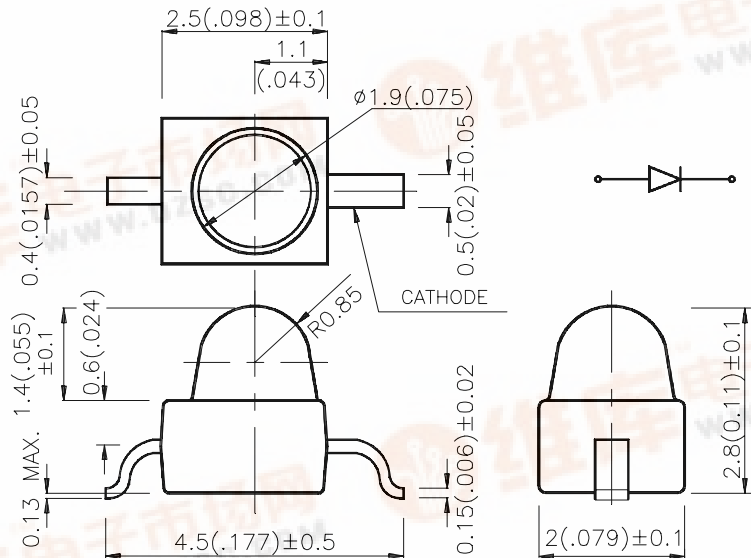
Features

- SUBMINIATURE PACKAGE.
- WIDE VIEWING ANGLE.
- GULL WING LEAD.
- LONG LIFE - SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- PACKAGE : 1000PCS / REEL.

Description

The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.
3. Lead spacing is measured where the lead emerge package.
4. Specifications are subject to change without notice.



### Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20 mA		Viewing Angle
			Min.	Typ.	2θ1/2
KM2520SGD03	SUPER BRIGHT GREEN (GaP)	GREEN DIFFUSED	2.6	10	40°

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

### Electrical / Optical Characteristics at T<sub>A</sub>=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ <sub>peak</sub>	Peak Wavelength	Super Bright Green	565		nm	I <sub>F</sub> =20mA
λ <sub>D</sub>	Dominate Wavelength	Super Bright Green	568		nm	I <sub>F</sub> =20mA
Δλ <sub>1/2</sub>	Spectral Line Half-width	Super Bright Green	30		nm	I <sub>F</sub> =20mA
C	Capacitance	Super Bright Green	15		pF	V <sub>F</sub> =0V;f=1MHz
V <sub>F</sub>	Forward Voltage	Super Bright Green	2.2	2.5	V	I <sub>F</sub> =20mA
I <sub>R</sub>	Reverse Current	Super Bright Green		10	μA	V <sub>R</sub> = 5V

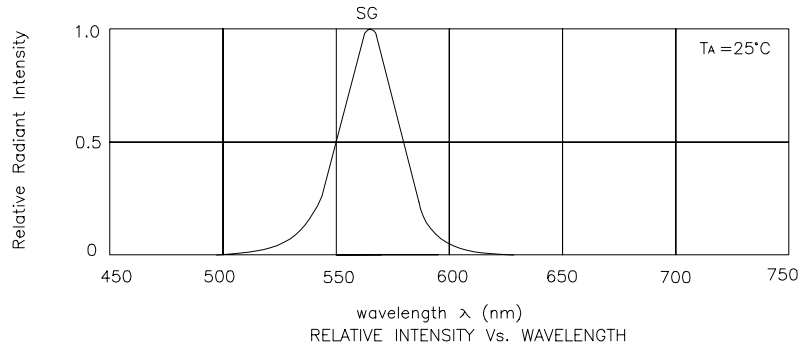
### Absolute Maximum Ratings at T<sub>A</sub>=25°C

Parameter	Super Bright Green	Units
Power dissipation	105	mW
DC Forward Current	25	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

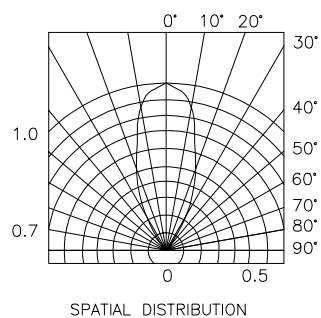
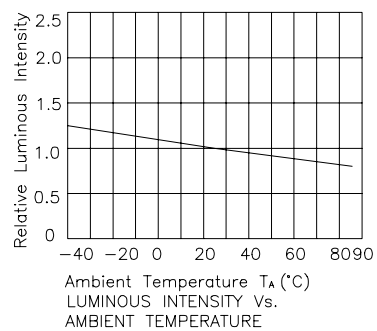
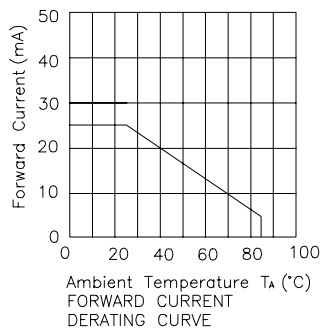
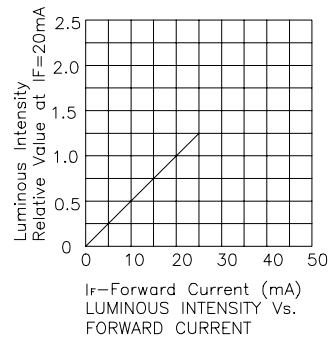
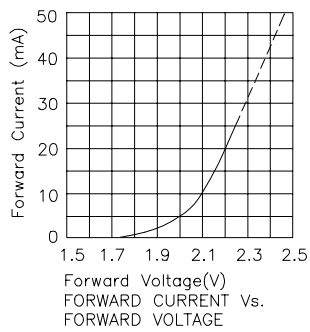
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

# Kingbright



## Super Bright Green KM2520SGD03

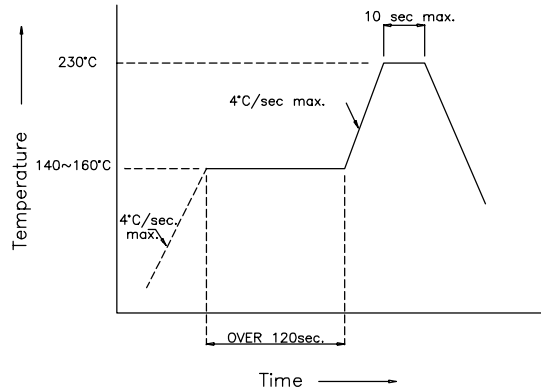


# Kingbright

## KM2520SGD03

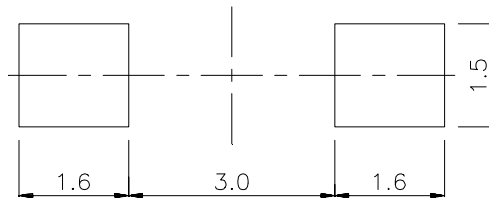
### SMT Reflow Soldering Instructions

Number of reflow process shall be less than 2 times and cooling process to normal temperature is required between first and second soldering process.



### Recommended Soldering Pattern

(Units : mm)



### Tape Specifications

(Units : mm)

